

Patent



Docket No. 1232-4421US1

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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**Applicant(s)** : UEHARA et al.  
**Serial No.** : 09/664,715      **Art Unit** : 1765  
**Filed** : September 19, 2000      **Examiner** : K. Chen  
**For** : WAFER PROCESSING APPARATUS, WAFER PROCESSING  
METHOD, AND SEMICONDUCTOR SUBSTRATE  
FABRICATION METHOD

**RESPONSE**

#13  
7/17/03  
mw

**MAIL STOP - Non-Fee Amendment**  
**COMMISSIONER FOR PATENTS**

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Sir:

Kindly consider this Response to the Office Action dated April 25, 2003, in the above-identified application.

**Remarks** begin on Page 2 of this paper.